

Application No. 10/012,210
Reply to Office Action dated June 7, 2004 and
Appeal Brief Filed April 12, 2005

Amendments to the Drawings:

The attached sheet of drawings includes new Figure 12.

Attachment: New Sheet

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REMARKS

Claims 1-21 will be pending upon entry of the present amendment.

The Examiner has objected to the drawings for not showing the first and second circuit boards as recited in various claims, and has indicated that the objection will not be held in abeyance. Accordingly, a new Figure 12 has been added, in which first and second connectors electrically couple first and second circuit boards. A paragraph of description for the new figure has been added, as well. Neither the new figure nor the new paragraph constitute new matter.

Adequate support for the amendment may be found in the specification. For example, beginning on page 3, line 23, the specification states, "Electrical traces 20, shown in Figure 2, in electrical contact with the contact pads, provide electrical coupling with other circuits or connectors, not shown." The specification also states, at page 4, line 10, "Flexible connectors are frequently employed to connect a circuit board to another circuit board or a peripheral device." Finally, a comparison of Figures 9 and 12 reveals that the pictured structures of Figure 12 are substantially identical to structures shown in Figure 9. Clearly, there is no new matter added with the present amendment.

Applicants request entry of the present amendment after final, in order to place the case in condition for consideration under appeal.

In the event the Examiner finds minor informalities that can be resolved by telephone conference, the Examiner is urged to contact applicants' undersigned representative at (206) 694-4848 in order to expeditiously resolve prosecution of this application.

The Director is authorized to charge any additional fees due by way of this Amendment, or credit any overpayment, to our Deposit Account No. 19-1090.

Respectfully submitted,

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